amended Claims

1. A device for coating of an inner circular surface (7i) of a coating surface (3b) of a carrier wafer (3) with a coating material (9) being antiadhesion material with the following features:

- an application means (5) for applying the coating material (9) intended for coating of the inner circular surface (7i) to the inner circular surface (7i), and
- a rotating means (2, 6) for accommodating and rotating the carrier wafer (3) around an axis (R) of rotation and for distribution of the coating material (9) on the coating surface (3b),

characterized in that the second application means (4) has controlling means for applying a coating inhibitor which at least inhibits the coating of the outer circular ring surface (7a) during the distribution of the coating material (9) to an outer circular ring surface (7a) which surrounds the inner circular surface (7i).

2. The device as claimed in Claim 1, wherein the coating inhibitor is a solvent which can dissolve the coating material (9).

3. The device as claimed in one of the preceding claims, wherein the first application means (5) is arranged or can be arranged such that the application of the coating material (9) takes place in the region of the rotation axis (R) of rotation, especially concentrically to the carrier wafer (1).

4. The device as claimed in one of the preceding claims, wherein the second application means is arranged or can be arranged such that the application of the coating inhibitor takes place at least in one peripheral section (7u) of the outer circular ring surface (7a) in the region of a radially inside edge (7r) of the outer circular ring surface (7a).

5. The device as claimed in one of the preceding claims, wherein there are control means for

controlling application amounts and/or application pressure and/or application speed and/or application angles and/or application instants of the first and/or second application means (4, 5).

6. The device as claimed in one of the preceding claims, wherein there are curing agents for curing of the coating material (9).

7. The device as claimed in one of the preceding claims, wherein the second application means (4) have at least one line (41) which can be arranged pointing with one outlet end (4e) toward the circular ring surface (7a).

8. The device as claimed in one of the preceding claims, wherein the second application means (4) have especially on each outlet end (4e) an especially controllable nozzle (4d).

9. A method for coating of an inner circular surface (7i) of a coating surface (3b) of a carrier wafer (3) with a coating material (9) being an antiadhesion material with the following steps, especially the following sequence:

- application of the coating material (9) to the inner circular surface (7i) by the first application means (5) and distribution of the coating material by rotating the carrier wafer (3) around the axis (R) of rotation by rotating means (2, 6),

wherein during the distribution of the coating material (9) by the second application means (4) an outer circular ring surface (7a) which surrounds the inner circular surface (7i) is supplied with a coating inhibitor which at least inhibits the coating of the outer circular ring surface (7a).

10. The method as claimed in Claim 9, wherein the coating material (9) is applied in the region of the axis (R) of rotation especially concentrically to the carrier wafer (1).

11. The method as claimed in Claim 9 or 10, wherein the application of the solvent at least in one peripheral section (7u) of the outer circular ring surface (7a) takes place in the region of a radially inner edge (7r) of the outer circular ring surface (7a), especially offset in time for application of the coating material (9).

## CLAIMS

1. A method for coating of an inner circular surface (7i) of a coating surface (3b) of a carrier wafer (3) with a coating material (9), the method comprising the steps of:

application of the coating material (9) to the inner circular surface (7i) by a first application means (5) and distribution of the coating material (9) by rotating the carrier wafer (3) around an axis (R) of rotation by rotating means (2, 6),

wherein during the distribution of the coating material (9) by a second application means (4) an outer circular ring surface (7a) which surrounds the inner circular surface (7i) is applied with a coating inhibitor which at least inhibits the coating of the outer circular ring surface (7a).

2. The method of claim 1, wherein the applications of the coating material (9) and the coating inhibitor are controlled by an activation sequence and a deactivation sequence.

3. The method of claim 2, wherein the activation sequence calls for the coating inhibitor to be applied at instants selected from the group consisting of at latest until the coating material is reached, at the same time with the coating material and prior to the coating material.

4. The method of claim 2, wherein the deactivation sequence calls for the coating with the coating material to end before coating with the coating inhibitor.

5. The method as claimed in one of the preceding claims, further comprising a step of controlling application amounts and/or application pressure and/or application speed and/or application angles and/or application instants of the first and/or second application means (4, 5).

6. The method as claimed in one of the preceding claims, further comprising a step of curing the coating material (9) with curing agents.

7. The method as claimed in one of the preceding claims, wherein the second application means (4) comprises at least one line (41) which can be arranged pointing with one outlet end (4e) toward the circular ring surface (7a).

8. The method as claimed in one of the preceding claims, wherein the second application means (4) comprises on each outlet end (4e) a controllable nozzle (4d).

9. The method as claimed in one of the preceding claims, wherein the coating material (9) is applied in the region of the axis (R) of rotation especially concentrically to the carrier wafer (1).

10. The method as claimed in one of the preceding claims, wherein the application of the coating inhibitor at least in one peripheral section (7u) of the outer circular ring surface (7a) takes place in the region of a radially inner edge (7r) of the outer circular ring surface (7a), which is offset in time for application of the coating material (9).